Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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International
IOR Rectifier

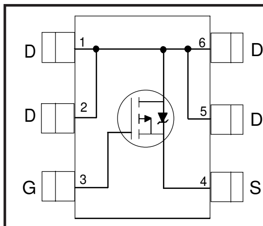
PD - 93997A

IRF5806

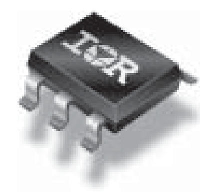
HEXFET® Power MOSFET

- Ultra Low On-Resistance
- P-Channel MOSFET
- Surface Mount
- Available in Tape & Reel
- Low Gate Charge

V_{DSS}	$R_{DS(on)}$ max	I_D
-20V	86mΩ@V_{GS} = -4.5V	-4.0A
	147mΩ@V_{GS} = -2.5V	-3.0A



Top View


TSOP-6

Description

These P-channel MOSFETs from International Rectifier utilize advanced processing techniques to achieve the extremely low on-resistance per silicon area. This benefit provides the designer with an extremely efficient device for use in battery and load management applications.

The TSOP-6 package with its customized leadframe produces a HEXFET® power MOSFET with $R_{DS(on)}$ 60% less than a similar size SOT-23. This package is ideal for applications where printed circuit board space is at a premium. It's unique thermal design and $R_{DS(on)}$ reduction enables a current-handling increase of nearly 300% compared to the SOT-23.

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain-Source Voltage	-20	V
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ -4.5V	-4.0	A
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ -4.5V	-3.3	
I_{DM}	Pulsed Drain Current①	-16.5	
P_D @T_A = 25°C	Maximum Power Dissipation③	2.0	W
P_D @T_A = 70°C	Maximum Power Dissipation③	1.3	W
	Linear Derating Factor	0.02	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
T_J , T_{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

Thermal Resistance

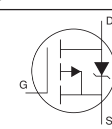
	Parameter	Max.	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient③	62.5	°C/W

1/22/03

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-20	——	——	V	V_{GS} = 0V, I_D = -250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	——	0.011	——	V/°C	Reference to 25°C, I_D = -1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	——	47.1	86	mΩ	V_{GS} = -4.5V, I_D = -4.0A ②
		——	67.5	147		V_{GS} = -2.5V, I_D = -3.0A ②
$V_{GS(th)}$	Gate Threshold Voltage	-0.45	——	-1.2	V	V_{DS} = V_{GS}, I_D = -250µA
g_{fs}	Forward Transconductance	6.4	——	——	S	V_{DS} = -10V, I_D = -4.0A
I_{DSS}	Drain-to-Source Leakage Current	——	——	-15	µA	V_{DS} = -16V, V_{GS} = 0V
		——	——	-25		V_{DS} = -16V, V_{GS} = 0V, T_J = 70°C
I_{GSS}	Gate-to-Source Forward Leakage	——	——	-100	nA	V_{GS} = -12V
	Gate-to-Source Reverse Leakage	——	——	100		V_{GS} = 12V
Q_g	Total Gate Charge	——	8.3	11.4	nC	I_D = -4.0A
Q_{gs}	Gate-to-Source Charge	——	1.2	——		V_{DS} = -16V
Q_{gd}	Gate-to-Drain ("Miller") Charge	——	2.6	——		V_{GS} = -4.5V
$t_{d(on)}$	Turn-On Delay Time	——	6.2	9.3	ns	V_{DD} = -10V, V_{GS} = -4.5V
t_r	Rise Time	——	27	41		I_D = -1.0A
$t_{d(off)}$	Turn-Off Delay Time	——	94	140		R_G = 6.0Ω
t_f	Fall Time	——	126	190		R_D = 10Ω ②
C_{iss}	Input Capacitance	——	594	——	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	——	114	——		V_{DS} = -15V
C_{rss}	Reverse Transfer Capacitance	——	87	——		f = 1.0MHz

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	——	——	-2.0	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	——	——	-16.5		
V_{SD}	Diode Forward Voltage	——	——	-1.2	V	T_J = 25°C, I_S = -2.0A, V_{GS} = 0V ②
t_{rr}	Reverse Recovery Time	——	116	174	ns	T_J = 25°C, I_F = -2.0A
Q_{rr}	Reverse Recovery Charge	——	90	135	nC	di/dt = -100A/µs ②

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width ≤ 300µs; duty cycle ≤ 2%.

③ When mounted on 1 inch square Copper board, t ≤ 10sec.

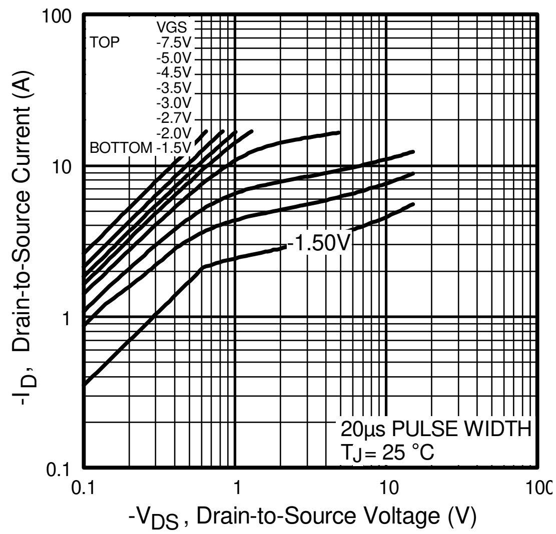


Fig 1. Typical Output Characteristics

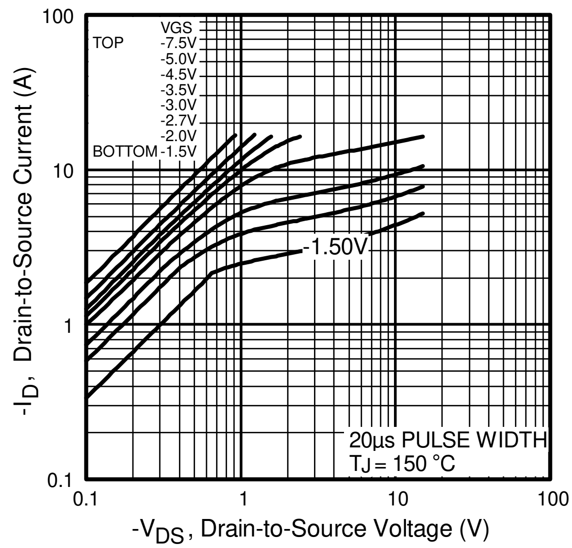


Fig 2. Typical Output Characteristics

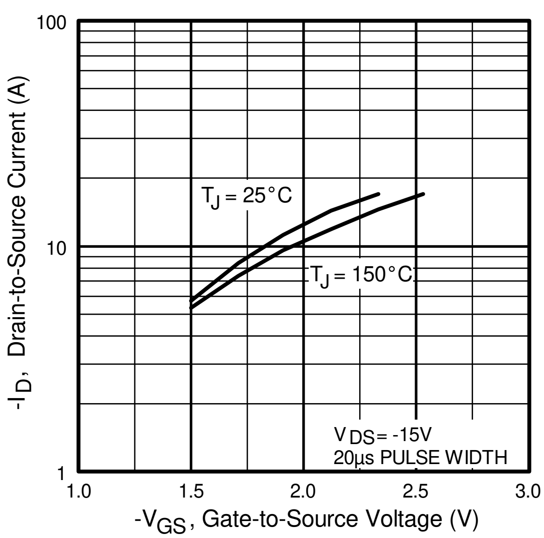


Fig 3. Typical Transfer Characteristics

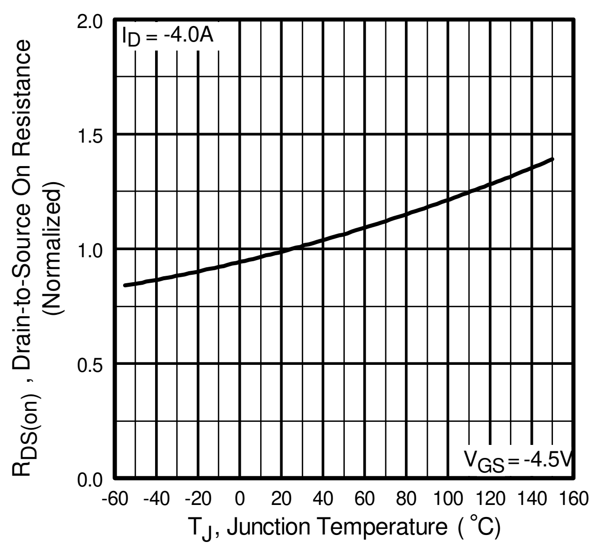


Fig 4. Normalized On-Resistance Vs. Temperature

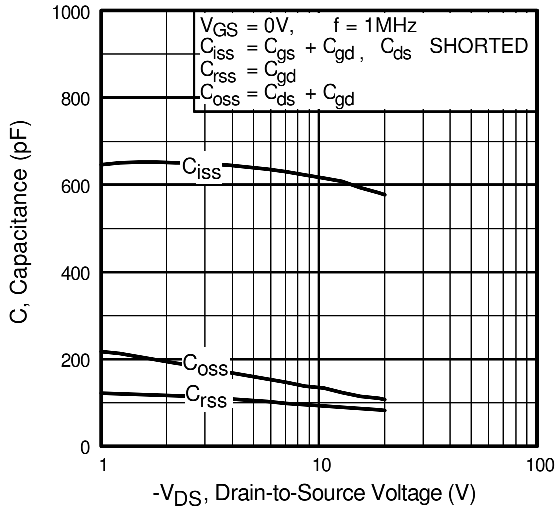


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

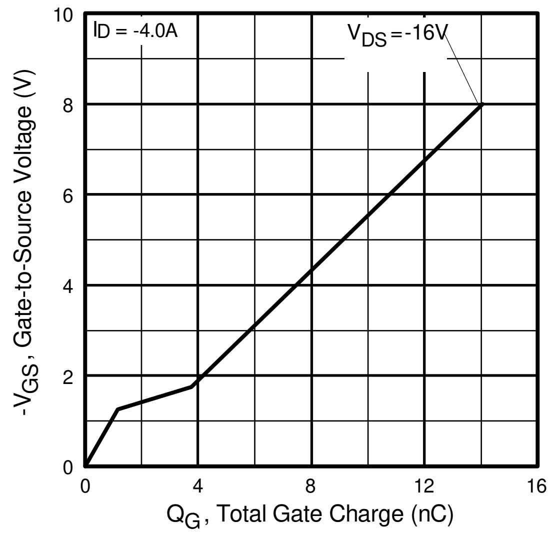


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

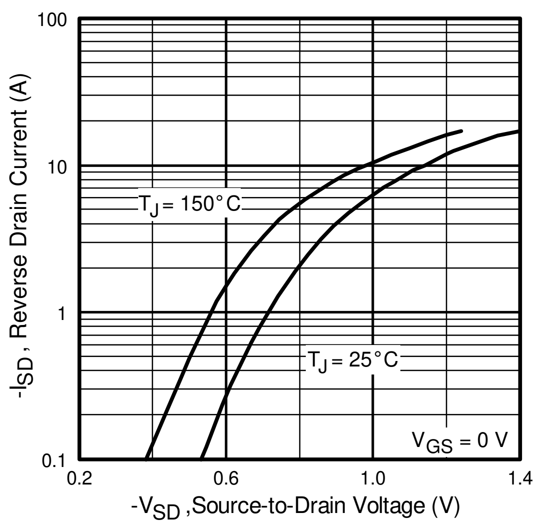


Fig 7. Typical Source-Drain Diode Forward Voltage

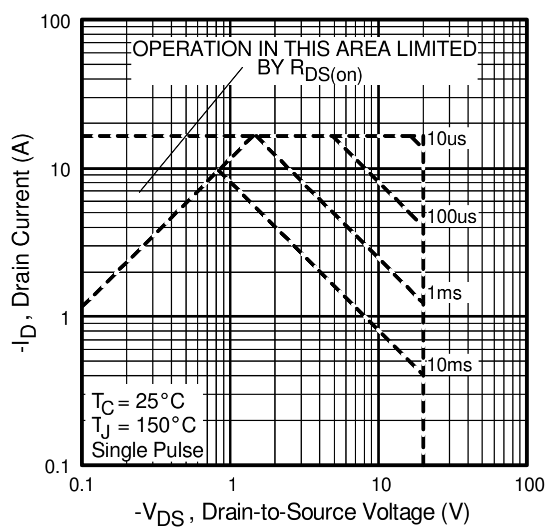


Fig 8. Maximum Safe Operating Area

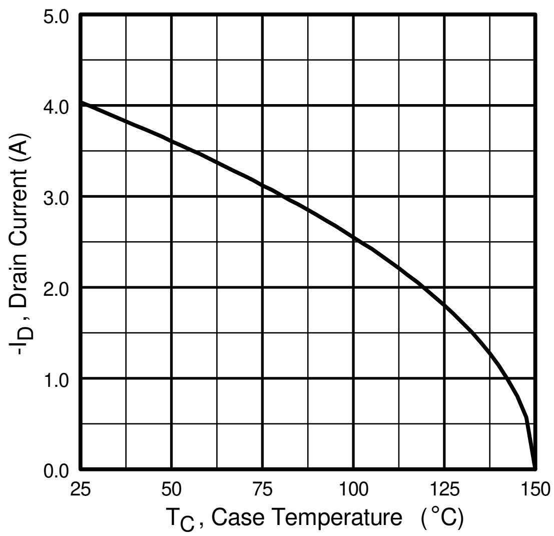


Fig 9. Maximum Drain Current Vs. Case Temperature

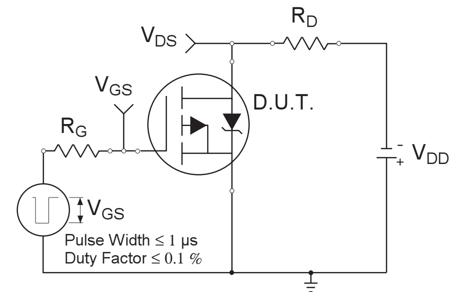


Fig 10a. Switching Time Test Circuit

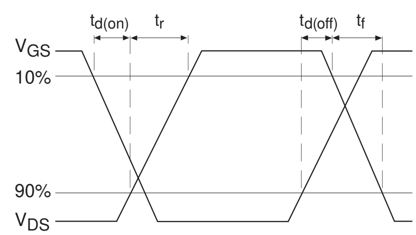


Fig 10b. Switching Time Waveforms

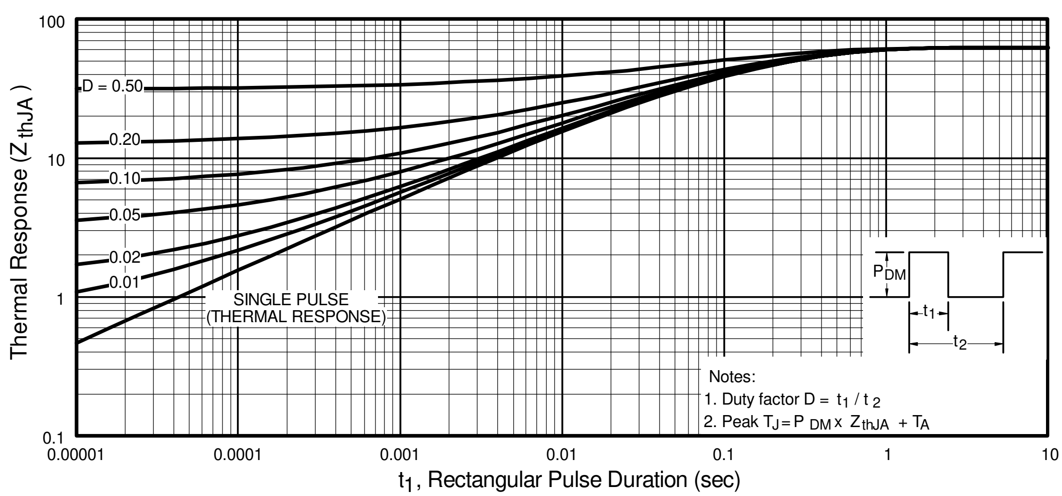


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

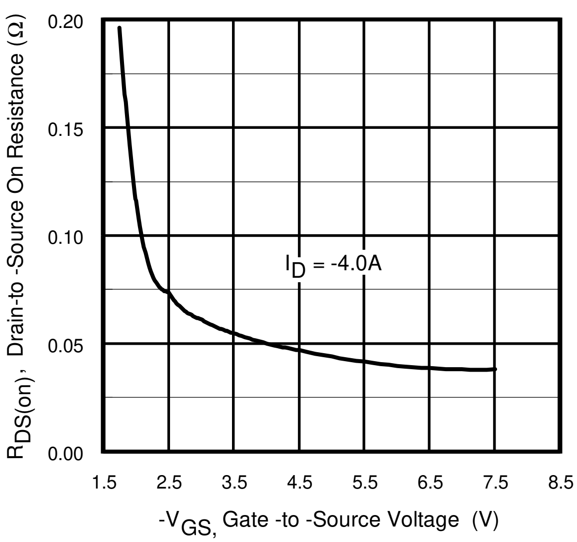


Fig 12. Typical On-Resistance Vs. Gate Voltage

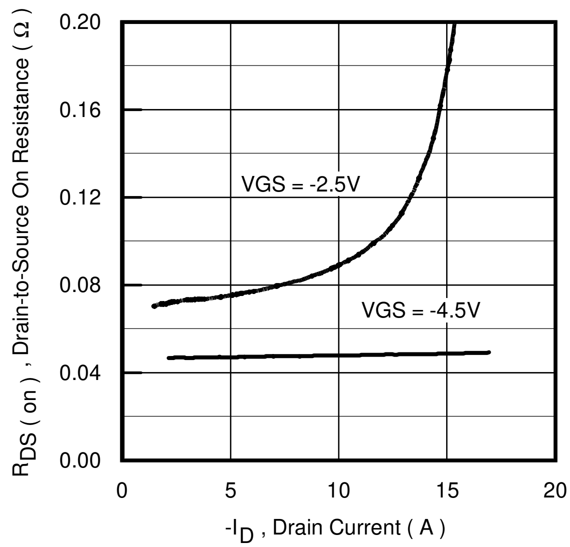


Fig 13. Typical On-Resistance Vs. Drain Current

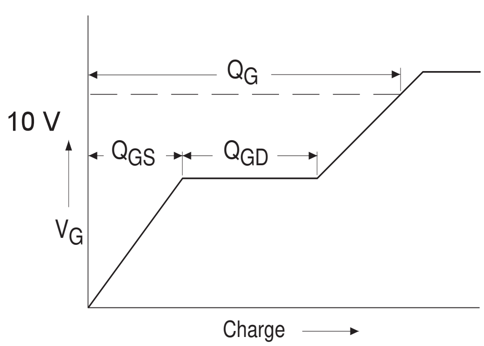


Fig 14a. Basic Gate Charge Waveform

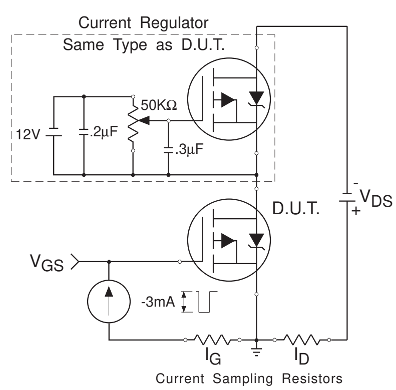


Fig 14b. Gate Charge Test Circuit

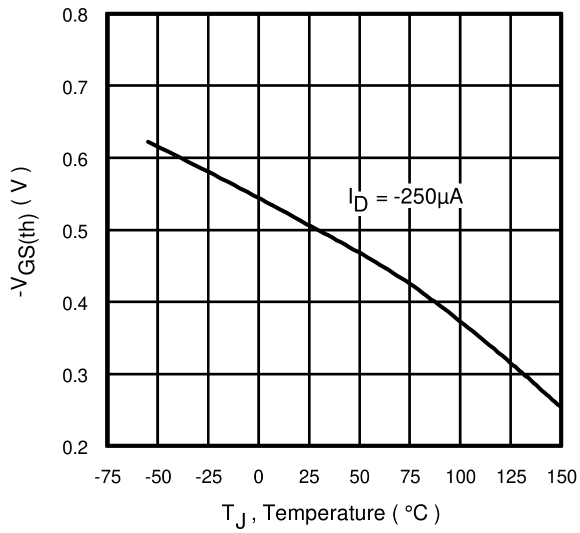


Fig 15. Typical Vgs(th) Vs. Junction Temperature

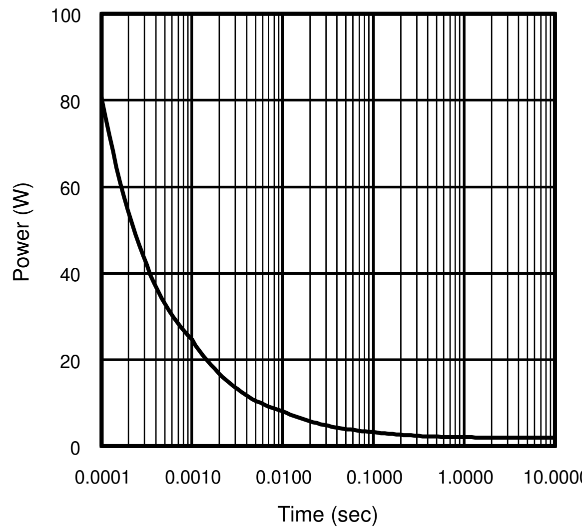
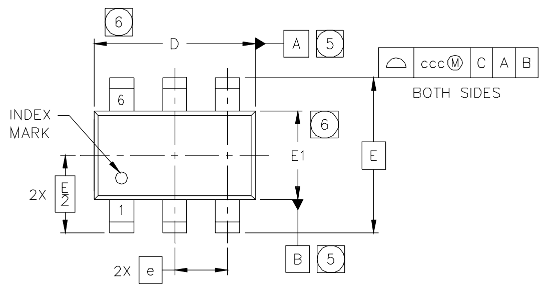
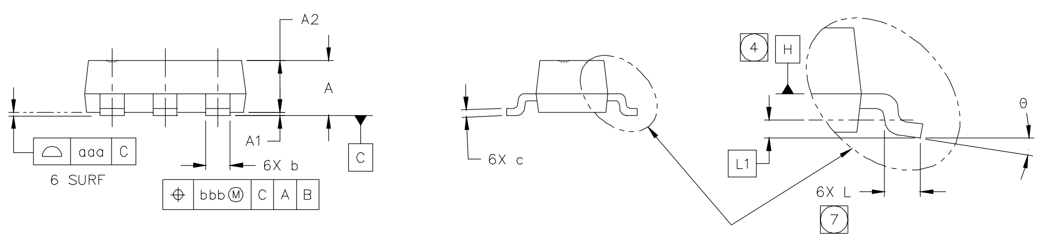


Fig 16. Typical Power Vs. Time

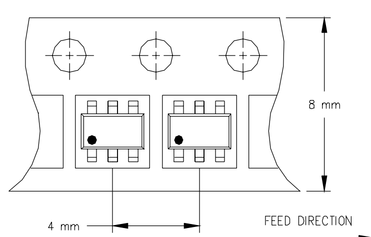
TSOP-6 Package Outline



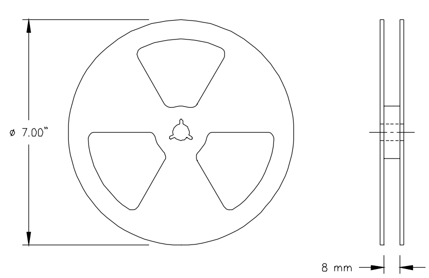
SYMBOL	MO-193AA DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	---	---	1.10	---	---	.0433
A1	0.01	---	0.10	.0004	---	.0039
A2	0.80	0.90	1.00	.0315	.0354	.0393
b	0.25	---	0.50	.0099	---	.0196
c	0.10	---	0.26	.004	---	.010
D	2.90	3.00	3.10	.115	.118	.122
E	2.75 BSC			.108 BSC		
E1	1.30	1.50	1.70	.052	.059	.066
e	1.00 BSC			.039 BSC		
L	0.20	0.40	0.60	.0079	.0157	.0236
L1	0.30 BSC			.0118 BSC		
θ	0°	---	8°	0°	---	8°
aaa	0.10			.004		
bbb	0.15			.006		
ccc	0.25			.010		



TSOP-6 Tape & Reel Information



NOTES:
1. OUTLINE CONFORMS TO EIA-481 & EIA-541.

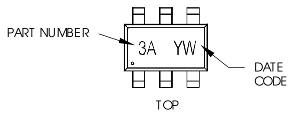


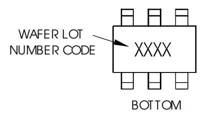
NOTES:
1. OUTLINE CONFORMS TO EIA-481 & EIA-541.

TSOP-6 Part Marking Information

Notes: This part marking information applies to devices produced before 02/26/2001

EXAMPLE: THIS IS AN SI3443DV





PART NUMBER CODE REFERENCE:

3A = SI3443DV
3B = IRF5800
3C = IRF5850
3D = IRF5851
3E = IRF5852
3I = IRF5805
3J = IRF5806

DATE CODE EXAMPLES:

YWW = 9603 = 6C
YWW = 9632 = FF

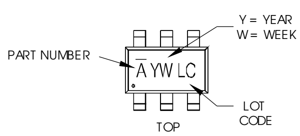
WW = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR

YEAR	Y	WORK WEEK	W
2001	1	01	A
2002	2	02	B
2003	3	03	C
2004	4	04	D
2005	5		
1996	6	↓	↓
1997	7		
1998	8		
1999	9		
2000	0	24	X
		25	Y
		26	Z

WW = (27-52) IF PRECEDED BY A LETTER

YEAR	Y	WORK WEEK	W
2001	A	27	A
2002	B	28	B
2003	C	29	C
2004	D	30	D
2005	E		
1996	F	↓	↓
1997	G		
1998	H		
1999	J		
2000	K	50	X
		51	Y
		52	Z

Notes: This part marking information applies to devices produced after 02/26/2001



W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR

YEAR	Y	WORK WEEK	W
2001	1	01	A
2002	2	02	B
2003	3	03	C
2004	4	04	D
2005	5		
1996	6	↓	↓
1997	7		
1998	8		
1999	9		
2000	0	24	X
		25	Y
		26	Z

PART NUMBER CODE REFERENCE:

$\overline{A}$ = SI3443DV
$\overline{B}$ = IRF5800
$\overline{C}$ = IRF5850
$\overline{D}$ = IRF5851
$\overline{E}$ = IRF5852
$\overline{I}$ = IRF5805
$\overline{J}$ = IRF5806
$\overline{K}$ = IRF5810
$\overline{L}$ = IRF5804
$\overline{M}$ = IRF5803
$\overline{N}$ = IRF5820

W = (27-52) IF PRECEDED BY A LETTER

YEAR	Y	WORK WEEK	W
2001	A	27	A
2002	B	28	B
2003	C	29	C
2004	D	30	D
2005	E		
1996	F	↓	↓
1997	G		
1998	H		
1999	J		
2000	K	50	X
		51	Y
		52	Z

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IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
IR EUROPEAN REGIONAL CENTRE: 439/445 Godstone Rd, Whyteleafe, Surrey CR3 OBL, UK Tel: ++ 44 (0)20 8645 8000
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IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 011 451 0111
IR JAPAN: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo 171 Tel: 81 (0)3 3983 0086
IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994 Tel: ++ 65 (0)838 4630
IR TAIWAN:16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673 Tel: 886-(0)2 2377 9936

Data and specifications subject to change without notice. 1/03